



Ferrites and accessories

ELP cores
General information

Date: October 2022

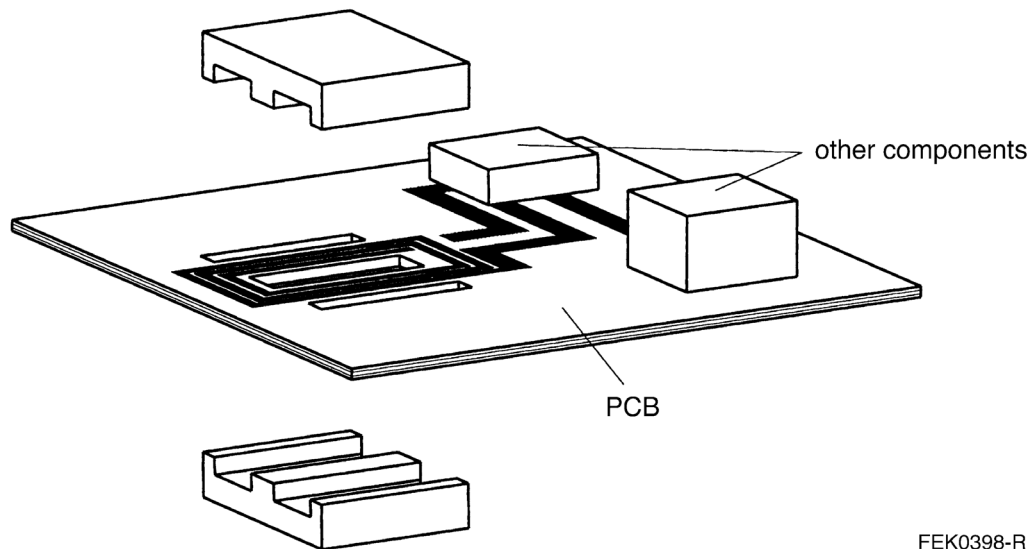
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Example of an assembly set ELP 32/6/20

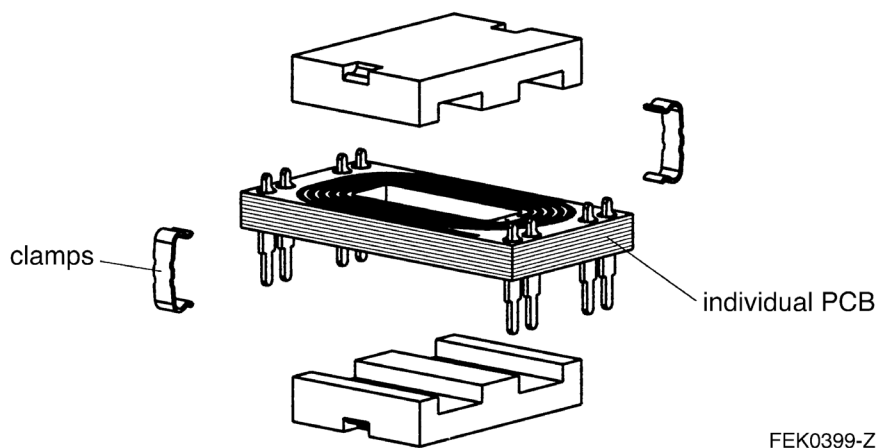
1 Total integration

Assembling by gluing technology (ELP without clamp recess)



2 Individual integration

Assembling by clamping technology (ELP with clamp recess)



ELP cores

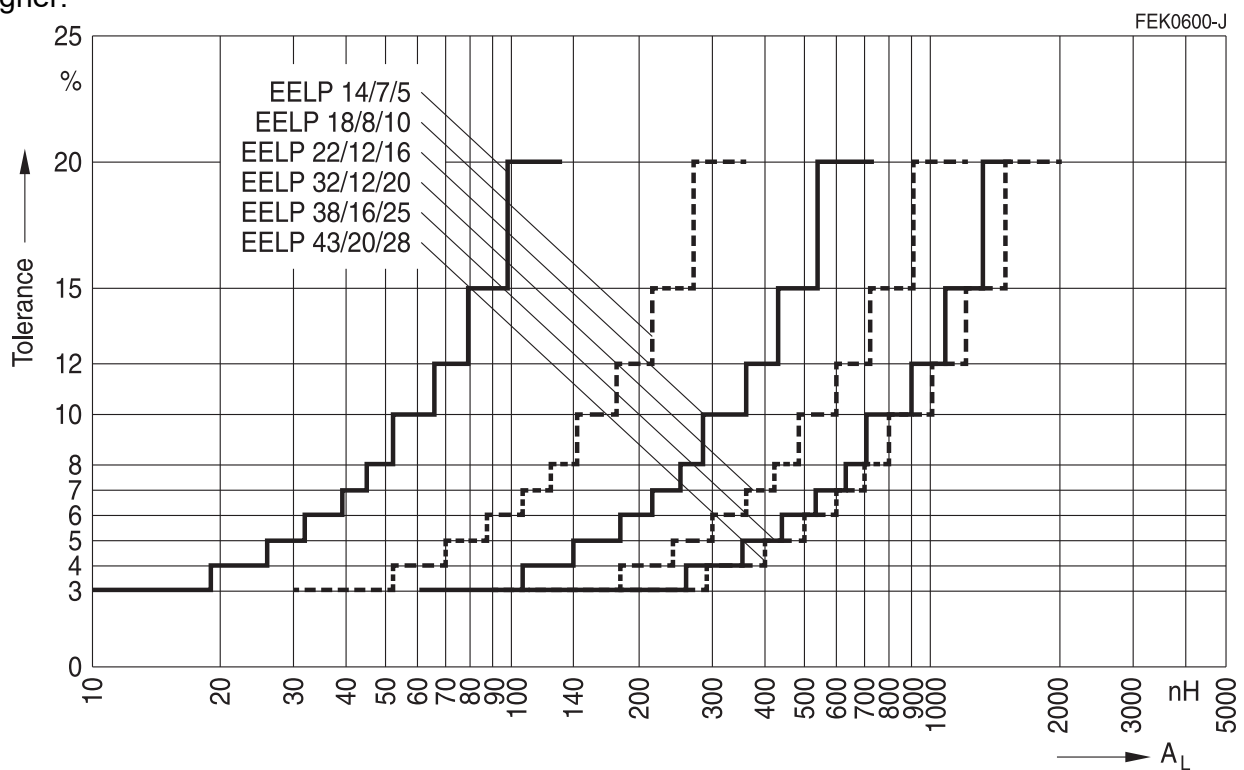
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3 Tolerances for ELP cores

The A_L value tolerances for ELP cores have consequently been defined with consideration of optimized process parameters for all materials with an initial permeability μ_i in the region of 2200 to 10000 as a step function (see figure below).

The “quantized” A_L step values should preferably be used. They are still available in their respective lower tolerance ranges. Thus a tolerance of $\pm 10\%$ can be determined for a EELP 32/12/20 made of N87 material for an A_L value of 600 nH.

With this type of tolerance definition, TDK Electronics has defined standard A_L values and the associated tolerance for the first time. Based on initial permeability tolerance can be slightly lower or higher.



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